

**Resistance to soldering temperature
for through-hole mounted devices**

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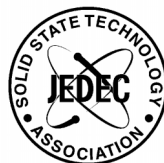
IEC/PAS 62174:2000

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PUBLICLY AVAILABLE SPECIFICATION



INTERNATIONAL
ELECTROTECHNICAL
COMMISSION



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EIA/JEDEC STANDARD

Test Method B106-B

Resistance to Soldering Temperature for Through-Hole Mounted Devices

JESD22-B106-B

(Revision of Test Method B106-A)

FEBRUARY 1999

ELECTRONIC INDUSTRIES ALLIANCE

JEDEC Solid State Technology Association



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INTERNATIONAL ELECTROTECHNICAL COMMISSION

RESISTANCE TO SOLDERING TEMPERATURE
FOR THROUGH-HOLE MOUNTED DEVICES

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IEC-PAS 62174 was submitted by JEDEC and has been processed by IEC technical committee 47: Semiconductor devices.

The text of this PAS is based on the following document:

This PAS was approved for publication by the P-members of the committee concerned as indicated in the following document:

Draft PAS	Report on voting
47/1447/PAS	47/1480/RVD

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